

Product Summary

RoHS

- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ 100% EAS Guaranteed
- ★ Advanced VD MOSFETS

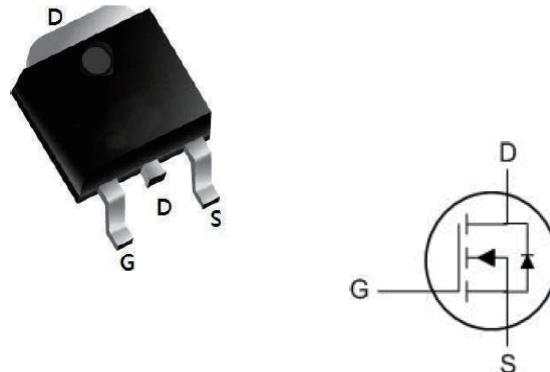
| BVDSS | RDS(on) | ID |
|-------|---------|----|
| 500V | 2.4mΩ | 4A |

Applications

The 4N50 is the Advanced VD N-ch MOSFETS, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The 4N50 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | | Max. | Units |
|-----------------------------------|---|------------------------|------------|-------|
| V _{DSS} | Drain-Source Voltage | | 500 | V |
| V _{GSS} | Gate-Source Voltage | | ±30 | V |
| I _D | Continuous Drain Current | T _C = 25°C | 4 | A |
| | | T _C = 100°C | 2 | A |
| I _{DM} | Pulsed Drain Current <small>(Note 1)</small> | | 15 | A |
| EAS | Single Pulsed Avalanche Energy <small>(Note 2)</small> | | 67 | mJ |
| I _{AR} | Avalanche Current <small>(Note 1)</small> | | 5 | A |
| EAR | Repetitive Avalanche Energy <small>(Note 1)</small> | | 6.4 | mJ |
| dV/dt | Peak Diode Recovery dV/dt <small>(Note 3)</small> | | 5 | V/ns |
| P _D | Power Dissipation | T _C = 25°C | 32.9 | W |
| | | Derate above 25°C | 0.2 | W/°C |
| T _L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | 300 | °C/W |
| T _J , T _{STG} | Operating and Storage Temperature Range | | -55 To 150 | °C |

Thermal Data

| Symbol | Parameter | Value | Units |
|------------------|---|-------|-------|
| R _{θJC} | Thermal Resistance, Junction-to-Case | 6.25 | °C/W |
| R _{θJS} | Thermal Resistance, Case-to-Sink Typ. | -- | °C/W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient | 62.5 | °C/W |

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Units |
|-----------|---------------------------------|--|------|------|-----------|---------------|
| V(BR)DSS | Drain-Source Breakdown | $V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$ | 500 | 550 | -- | V |
| IDSS | Zero Gate Voltage Drain Current | $V_{DS} = 650\text{V}, V_{GS} = 0\text{V}$, | -- | -- | 1 | μA |
| IGSS | Gate-Source Leakage | $V_{GS} = \pm 30\text{V}$ | -- | -- | ± 100 | nA |
| VGS(th) | Gate-Source Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250\mu\text{A}$ | 2 | 3 | 4 | V |
| RDS(on) | Drain-Source On-Resistance | $V_{GS} = 10\text{V}, I_D = 3.5\text{A}$ | -- | 2.4 | 3 | Ω |
| C_{iss} | Input Capacitance | $V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1.0\text{MHz}$ | -- | 310 | -- | pF |
| C_{oss} | Output Capacitance | | -- | 39 | -- | |
| C_{rss} | Reverse Transfer Capacitance | | -- | 6 | -- | |
| Q_g | Total Gate Charge | $V_{DD} = 400\text{V}, I_D = 3\text{A}, V_{GS} = 10\text{V}$ | -- | 8 | -- | nC |
| Q_{gs} | Gate-Source Charge | | -- | 1.2 | -- | |
| Q_{gd} | Gate-Drain Charge | | -- | 5 | -- | |
| td(on) | Turn-on Delay Time | $V_{DD} = 250\text{V}, I_D = 3\text{A}, R_G = 25\Omega$ | -- | 7.8 | -- | ns |
| t_r | Turn-on Rise Time | | -- | 33 | -- | |
| td(off) | Turn-off Delay Time | | -- | 23 | -- | |
| t_f | Turn-off Fall Time | | -- | 59 | -- | |
| IS | Continuous Body Diode Current | $T_c = 25^\circ\text{C}$ | -- | -- | 4 | A |
| ISM | Pulsed Diode Forward Current | | -- | -- | 12 | A |
| V_{SD} | Body Diode Voltage | $T_J = 25^\circ\text{C}, I_{SD} = 3\text{A}, V_{GS} = 0\text{V}$ | -- | -- | 1.4 | V |
| trr | Reverse Recovery Time | $V_{GS} = 0\text{V}, I_S = 3\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$ | -- | 80 | -- | ns |
| Qrr | Reverse Recovery Charge | | -- | 1.8 | -- | μC |

Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The EAS data shows Max. rating . $I_{AS} = 2.4\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
3. The test condition is Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Electrical and Thermal Characteristics (Curves)

Figure 1: Output Characteristics

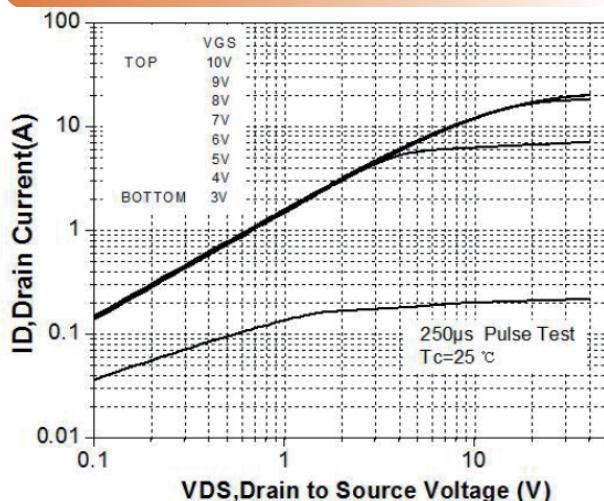


Figure 2: Typical Transfer Characteristics

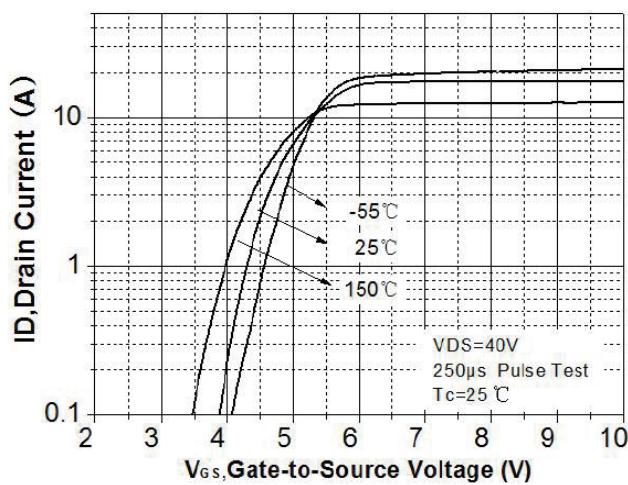


Figure 3: On-resistance vs. Drain Current

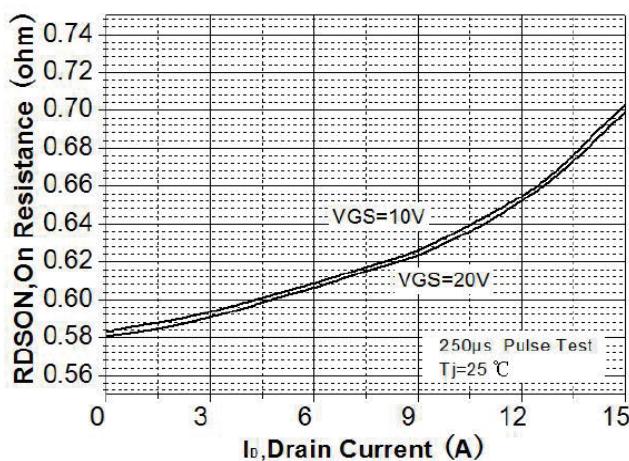


Figure 4: Body Diode Characteristics

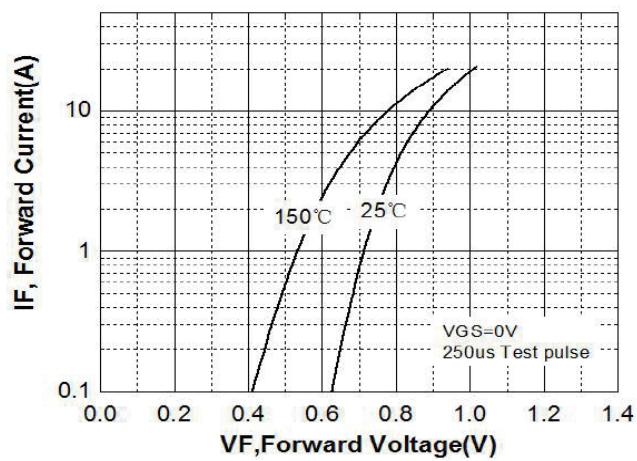


Figure 5: Capacitance Characteristics

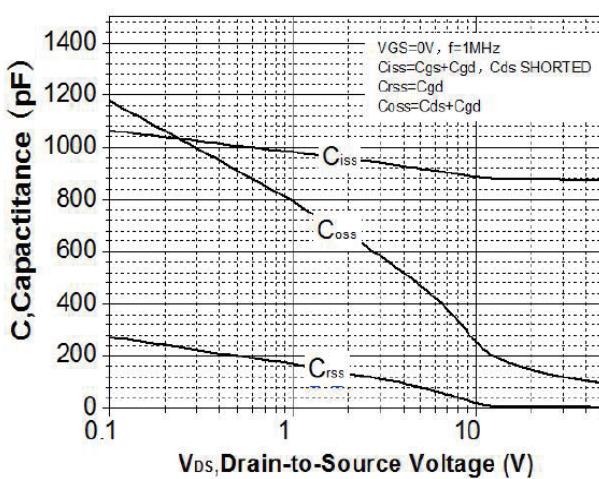
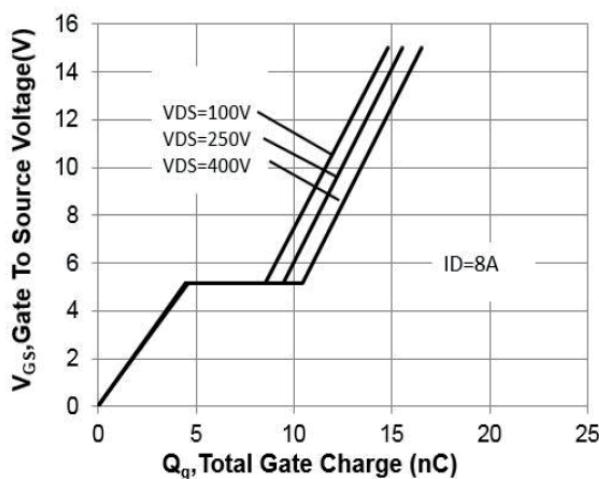


Figure 6: Gate Charge Characteristics



Typical Performance Characteristics

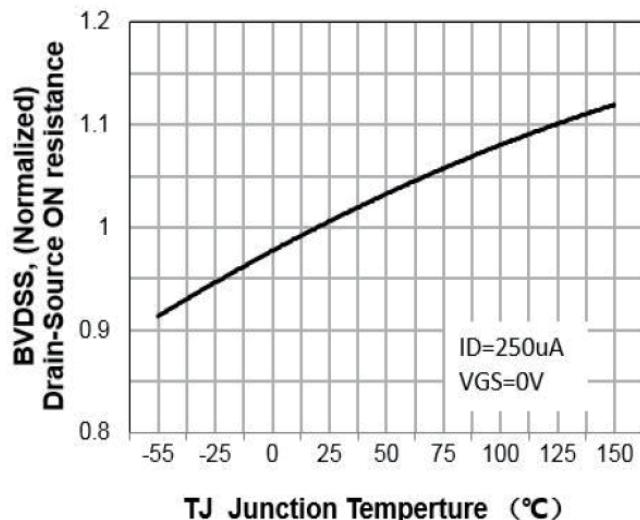
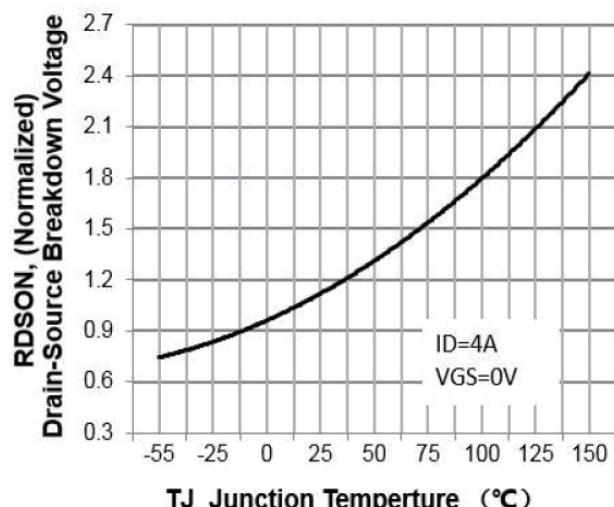
Figure 7: Breakdown Voltage Variation
4N50

Figure 8: On-Resistance Variation
4N50


Figure 9: Maximum Safe Operating Area

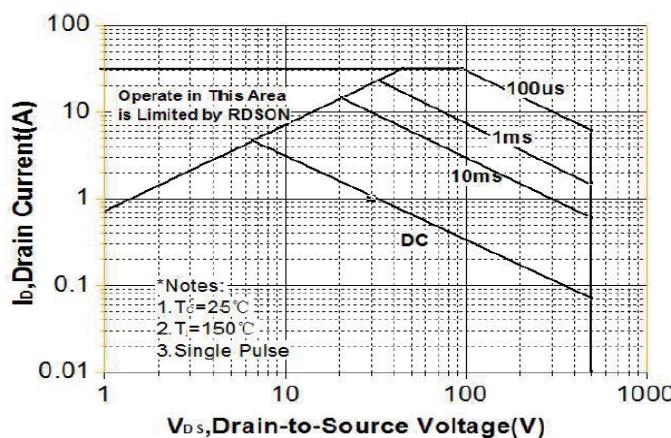
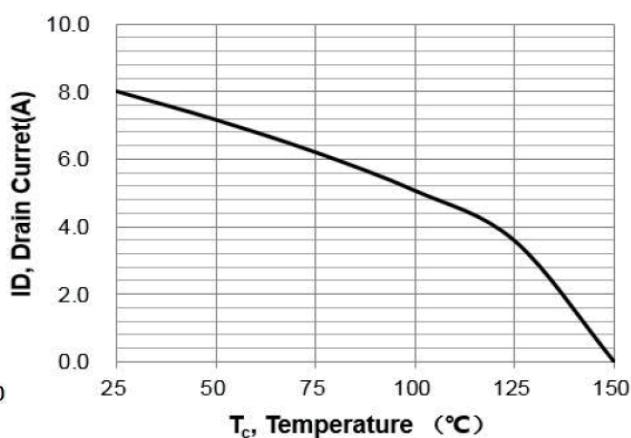
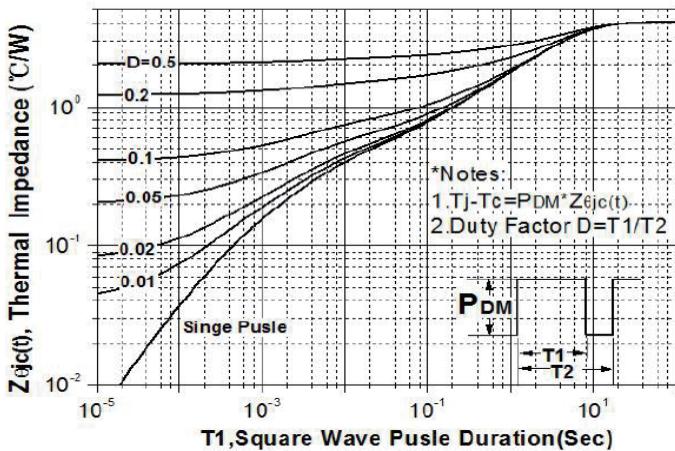
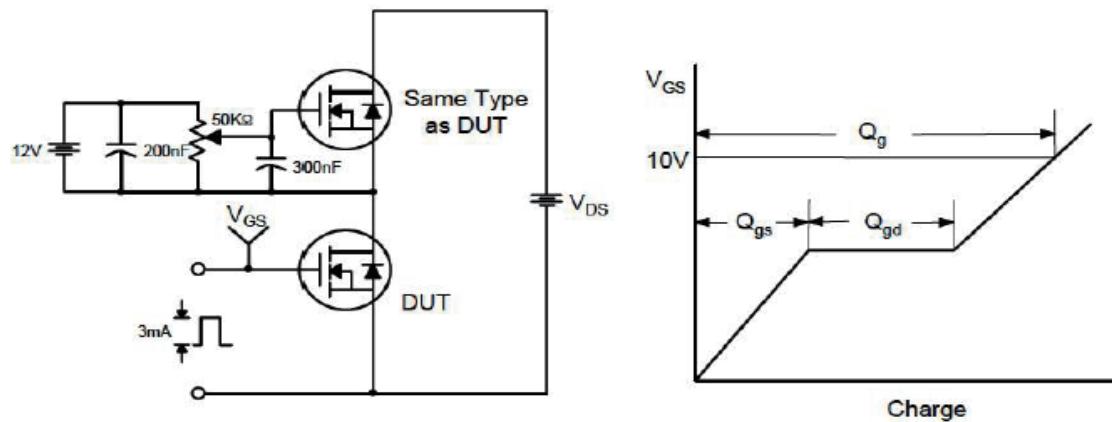
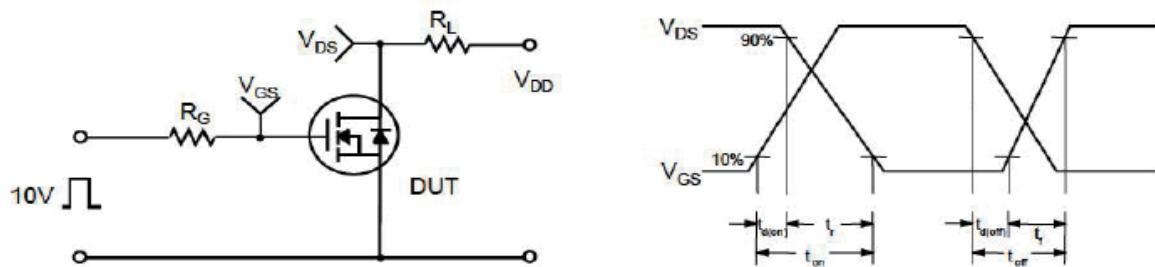
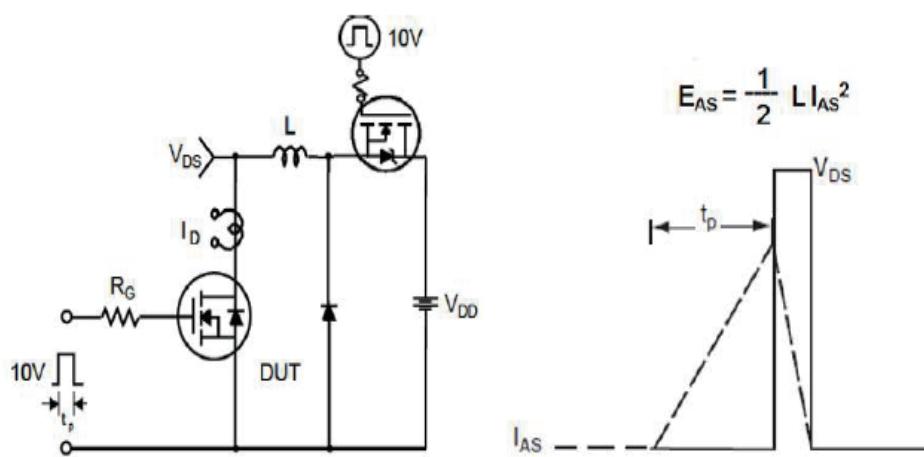

Figure 10: Maximum Drain Current
vs Temperature


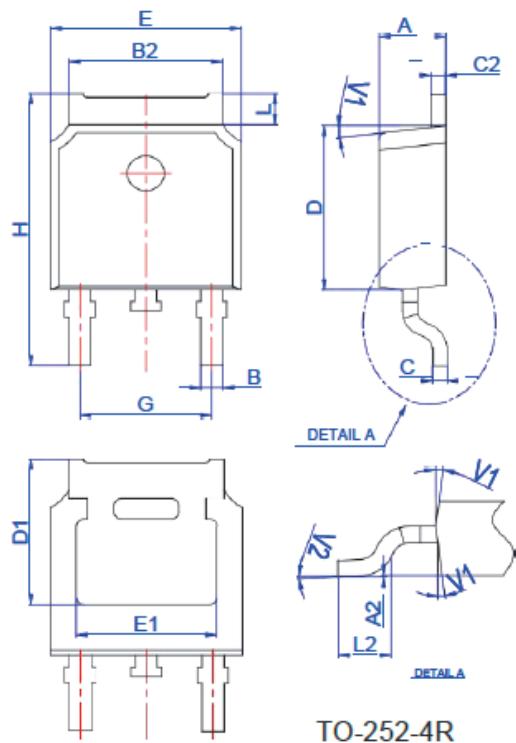
Figure 11: Transient Thermal Response C



Test circuit

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


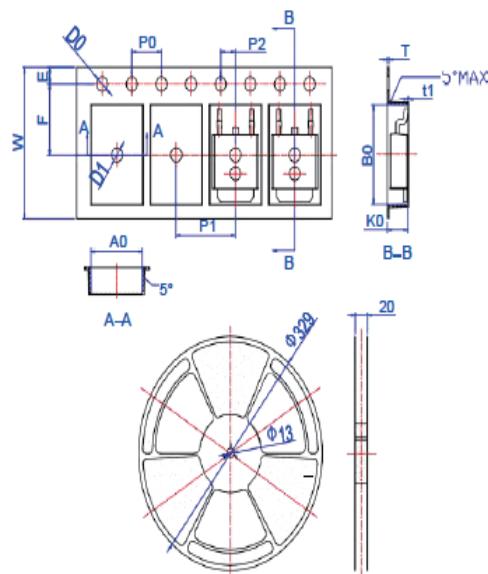
Package Mechanical Data-TO-252



| Ref. | Dimensions | | | | | |
|------|-------------|------|-------|----------|------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.10 | | 2.50 | 0.083 | | 0.098 |
| A2 | 0 | | 0.10 | 0 | | 0.004 |
| B | 0.66 | | 0.86 | 0.026 | | 0.034 |
| B2 | 5.18 | | 5.48 | 0.202 | | 0.216 |
| C | 0.40 | | 0.60 | 0.016 | | 0.024 |
| C2 | 0.44 | | 0.58 | 0.017 | | 0.023 |
| D | 5.90 | | 6.30 | 0.232 | | 0.248 |
| D1 | 5.30REF | | | 0.209REF | | |
| E | 6.40 | | 6.80 | 0.252 | | 0.268 |
| E1 | 4.63 | | | 0.182 | | |
| G | 4.47 | | 4.67 | 0.176 | | 0.184 |
| H | 9.50 | | 10.70 | 0.374 | | 0.421 |
| L | 1.09 | | 1.21 | 0.043 | | 0.048 |
| L2 | 1.35 | | 1.65 | 0.053 | | 0.065 |
| V1 | | 7° | | | 7° | |
| V2 | 0° | | 6° | 0° | | 6° |

TO-252-4R

Reel Specification-TO-252



| Ref. | Dimensions | | | | | |
|------|-------------|-------|-------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| W | 15.90 | 16.00 | 16.10 | 0.626 | 0.630 | 0.634 |
| E | 1.65 | 1.75 | 1.85 | 0.065 | 0.069 | 0.073 |
| F | 7.40 | 7.50 | 7.60 | 0.291 | 0.295 | 0.299 |
| D0 | 1.40 | 1.50 | 1.60 | 0.055 | 0.059 | 0.063 |
| D1 | 1.40 | 1.50 | 1.60 | 0.055 | 0.059 | 0.063 |
| P0 | 3.90 | 4.00 | 4.10 | 0.154 | 0.157 | 0.161 |
| P1 | 7.90 | 8.00 | 8.10 | 0.311 | 0.315 | 0.319 |
| P2 | 1.90 | 2.00 | 2.10 | 0.075 | 0.079 | 0.083 |
| A0 | 6.85 | 6.90 | 7.00 | 0.270 | 0.271 | 0.276 |
| B0 | 10.45 | 10.50 | 10.60 | 0.411 | 0.413 | 0.417 |
| K0 | 2.68 | 2.78 | 2.88 | 0.105 | 0.109 | 0.113 |
| T | 0.24 | | 0.27 | 0.009 | | 0.011 |
| t1 | 0.10 | | | 0.004 | | |
| 10P0 | 39.80 | 40.00 | 40.20 | 1.567 | 1.575 | 1.583 |

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[IRS2092STRPBF-EL](#) [IPS70R2K0CEAKMA1](#) [TK31J60W5,S1VQ\(O](#) [TK31J60W,S1VQ\(O](#) [TK16J60W,S1VQ\(O](#) [2SK2614\(TE16L1,Q\)](#)
[DMN1017UCP3-7](#) [EFC2J004NUZTDG](#) [P85W28HP2F-7071](#) [DMN1053UCP4-7](#) [NTE2384](#) [DMC2700UDMQ-7](#) [DMN2080UCB4-7](#)
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